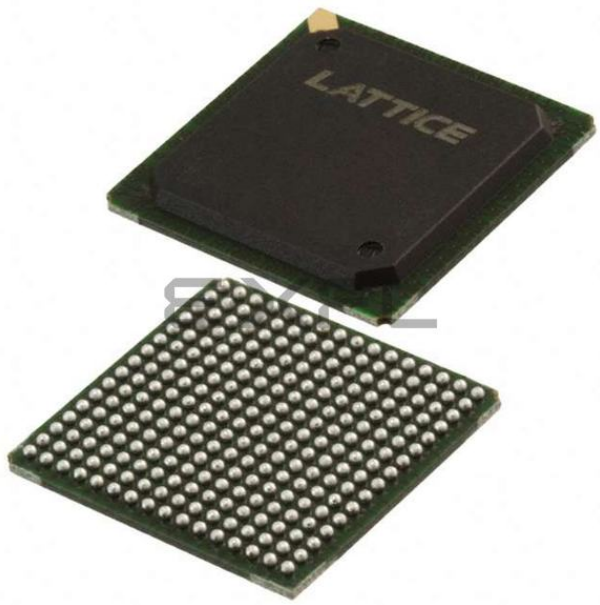
Lattice Semiconductor Corporation - M4A3-256/128-10FANI Datasheet



Welcome to E-XFL.COM

Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Not For New Designs
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	256
Number of Gates	-
Number of I/O	128
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a3-256-128-10fani

FUNCTIONAL DESCRIPTION

The fundamental architecture of ispMACH 4A devices (Figure 1) consists of multiple, optimized PAL® blocks interconnected by a central switch matrix. The central switch matrix allows communication between PAL blocks and routes inputs to the PAL blocks. Together, the PAL blocks and central switch matrix allow the logic designer to create large designs in a single device instead of having to use multiple devices.

The key to being able to make effective use of these devices lies in the interconnect schemes. In the ispMACH 4A architecture, the macrocells are flexibly coupled to the product terms through the logic allocator, and the I/O pins are flexibly coupled to the macrocells due to the output switch matrix. In addition, more input routing options are provided by the input switch matrix. These resources provide the flexibility needed to fit designs efficiently.

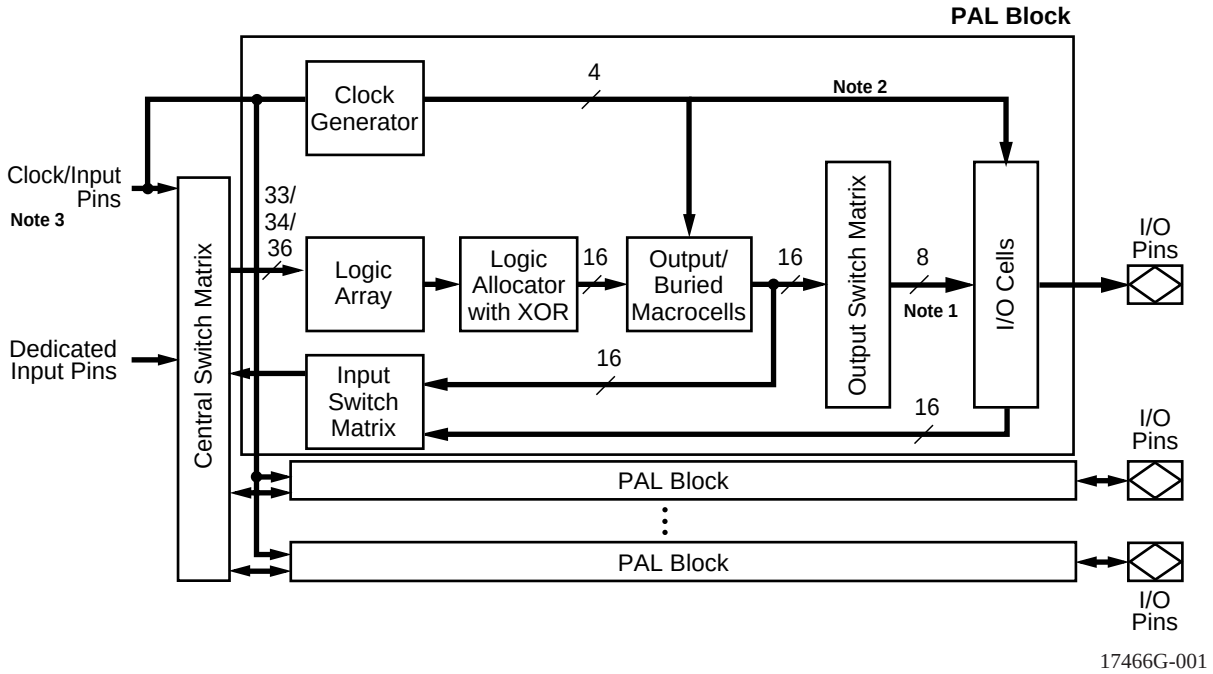


Figure 1. ispMACH 4A Block Diagram and PAL Block Structure

Notes:

1. *16 for ispMACH 4A devices with 1:1 macrocell-I/O cell ratio (see next page).*
2. *Block clocks do not go to I/O cells in M4A(3,5)-32/32.*
3. *M4A(3,5)-192, M4A(3,5)-256, M4A3-384, and M4A3-512 have dedicated clock pins which cannot be used as inputs and do not connect to the central switch matrix.*

Product-Term Array

The product-term array consists of a number of product terms that form the basis of the logic being implemented. The inputs to the AND gates come from the central switch matrix (Table 5), and are provided in both true and complement forms for efficient logic implementation.

Table 5. PAL Block Inputs

Device	Number of Inputs to PAL Block
M4A3-32/32 and M4A5-32/32	33
M4A3-64/32 and M4A5-64/32	33
M4A3-64/64	33
M4A3-96/48 and M4A5-96/48	33
M4A3-128/64 and M4A5-128/64	33
M4A3-192/96 and M4A5-192/96	34
M4A3-256/128 and M4A5-256/128	34
M4A3-256/160 and M4A3-256/192	36
M4A3-384	36
M4A3-512	36

Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in "product term clusters." The availability and distribution of product term clusters are automatically considered by the software as it fits functions within a PAL block. The size of a product term cluster has been optimized to provide high utilization of product terms, making complex functions using many product terms possible. Yet when few product terms are used, there will be a minimal number of unused—or wasted—product terms left over. The product term clusters available to each macrocell within a PAL block are shown in Tables 6 and 7.

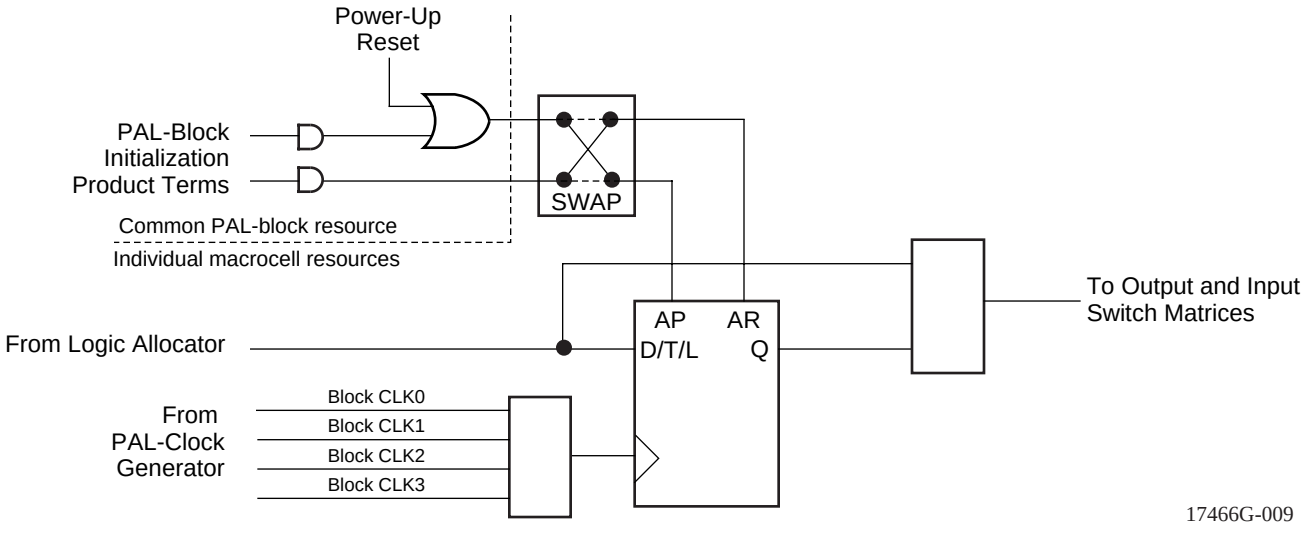
Each product term cluster is associated with a macrocell. The size of a cluster depends on the configuration of the associated macrocell. When the macrocell is used in synchronous mode (Figure 2a), the basic cluster has 4 product terms. When the associated macrocell is used in asynchronous mode (Figure 2b), the cluster has 2 product terms. Note that if the product term cluster is routed to a different macrocell, the allocator configuration is not determined by the mode of the macrocell actually being driven. The configuration is always set by the mode of the macrocell that the cluster will drive if not routed away, regardless of the actual routing.

In addition, there is an extra product term that can either join the basic cluster to give an extended cluster, or drive the second input of an exclusive-OR gate in the signal path. If included with the basic cluster, this provides for up to 20 product terms on a synchronous function that uses four extended 5-product-term clusters. A similar asynchronous function can have up to 18 product terms.

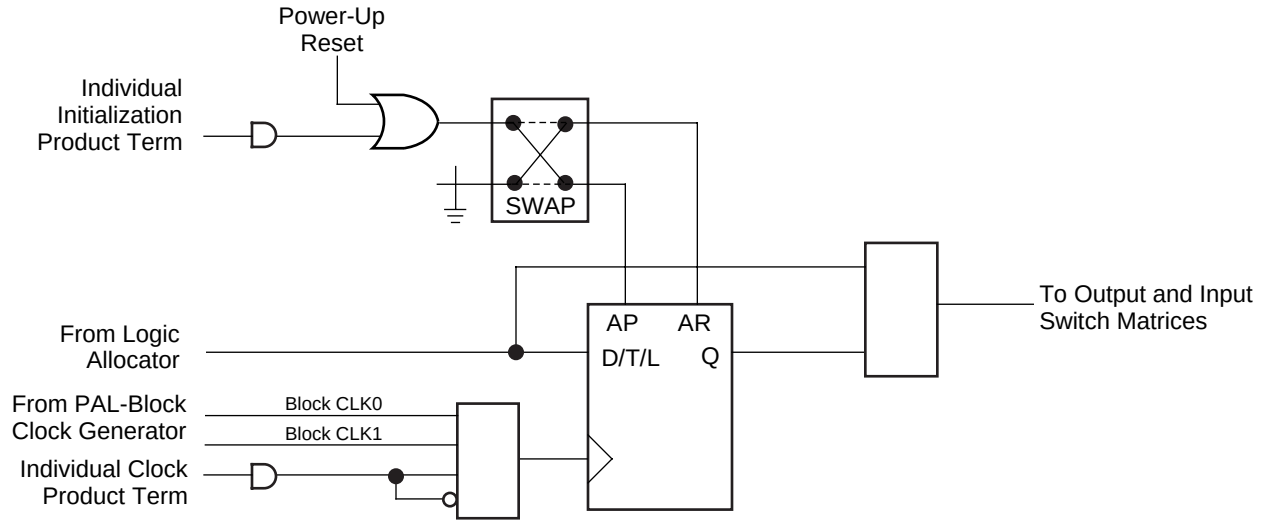
When the extra product term is used to extend the cluster, the value of the second XOR input can be programmed as a 0 or a 1, giving polarity control. The possible configurations of the logic allocator are shown in Figures 3 and 4.

Macrocell

The macrocell consists of a storage element, routing resources, a clock multiplexer, and initialization control. The macrocell has two fundamental modes: synchronous and asynchronous (Figure 5). The mode chosen only affects clocking and initialization in the macrocell.



a. Synchronous mode



b. Asynchronous mode

Figure 5. Macrocell

In either mode, a combinatorial path can be used. For combinatorial logic, the synchronous mode will generally be used, since it provides more product terms in the allocator.

Table 8. Register/Latch Operation

Configuration	Input(s)	CLK/LE [1]	Q+
D-type Register	D=X	0, 1, ↓ (↑)	Q
	D=0	↑ (↓)	0
	D=1	↑ (↓)	1
T-type Register	T=X	0, 1, ↓ (↑)	Q
	T=0	↑ (↓)	Q
	T=1	↑ (↓)	$\overline{Q}$
D-type Latch	D=X	1(0)	Q
	D=0	0(1)	0
	D=1	0(1)	1

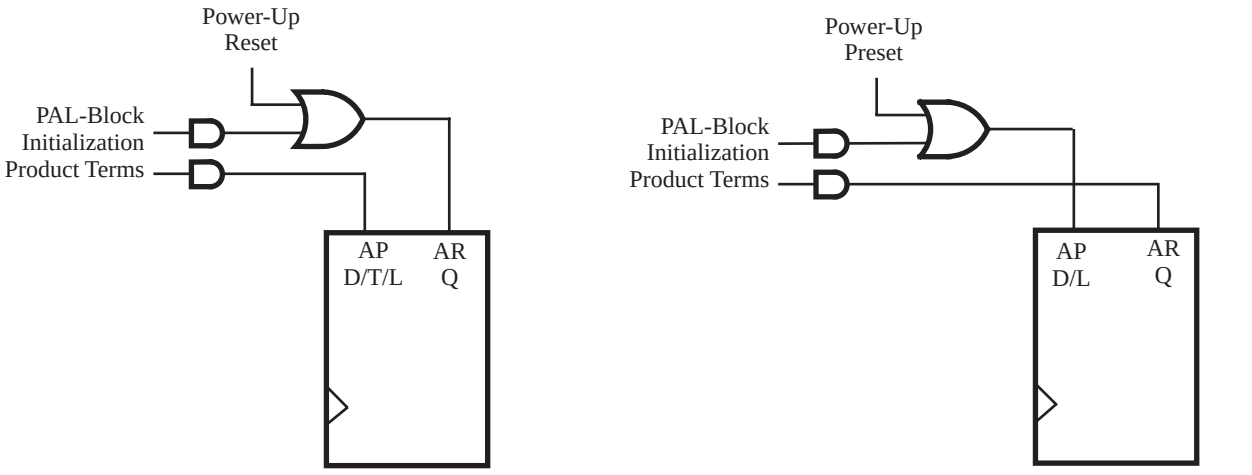
Note:

1. Polarity of CLK/LE can be programmed

Although the macrocell shows only one input to the register, the XOR gate in the logic allocator allows the D-, T-type register to emulate J-K, and S-R behavior. In this case, the available product terms are divided between J and K (or S and R). When configured as J-K, S-R, or T-type, the extra product term must be used on the XOR gate input for flip-flop emulation. In any register type, the polarity of the inputs can be programmed.

The clock input to the flip-flop can select any of the four PAL block clocks in synchronous mode, with the additional choice of either polarity of an individual product term clock in the asynchronous mode.

The initialization circuit depends on the mode. In synchronous mode (Figure 7), asynchronous reset and preset are provided, each driven by a product term common to the entire PAL block.



a. Power-up reset **b. Power-up preset**

17466G-012 17466G-013

Figure 7. Synchronous Mode Initialization Configurations

Output Switch Matrix

The output switch matrix allows macrocells to be connected to any of several I/O cells within a PAL block. This provides high flexibility in determining pinout and allows design changes to occur without effecting pinout.

In ispMACH 4A devices with 2:1 Macrocell-I/O cell ratio, each PAL block has twice as many macrocells as I/O cells. The ispMACH 4A output switch matrix allows for half of the macrocells to drive I/O cells within a PAL block, in combinations according to Figure 9. Each I/O cell can choose from eight macrocells; each macrocell has a choice of four I/O cells. The ispMACH 4A devices with 1:1 Macrocell-I/O cell ratio allow each macrocell to drive one of eight I/O cells (Figure 9).

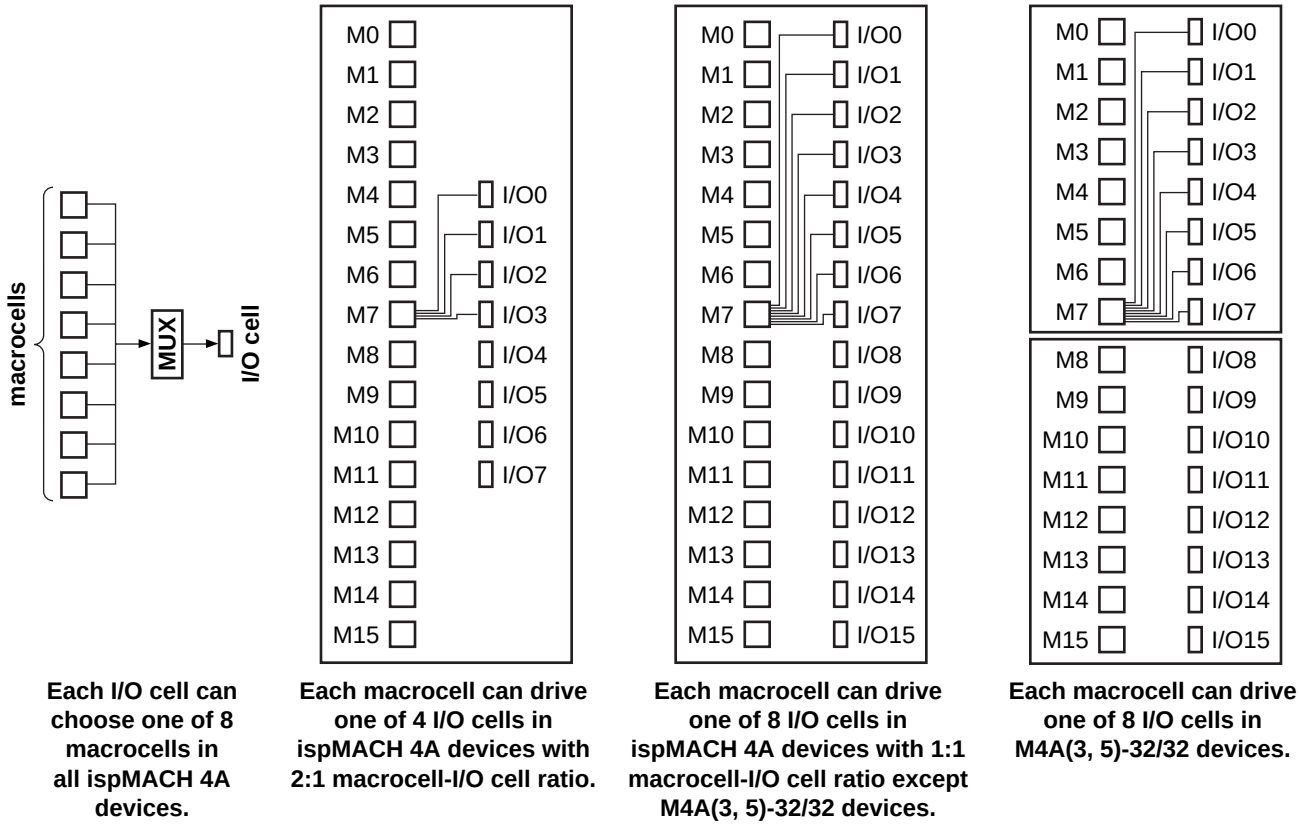


Figure 9. ispMACH 4A Output Switch Matrix

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routable to I/O Cells
M0, M1	I/O0, I/O5, I/O6, I/O7
M2, M3	I/O0, I/O1, I/O6, I/O7
M4, M5	I/O0, I/O1, I/O2, I/O7
M6, M7	I/O0, I/O1, I/O2, I/O3
M8, M9	I/O1, I/O2, I/O3, I/O4
M10, M11	I/O2, I/O3, I/O4, I/O5

I/O Cell

The I/O cell (Figures 10 and 11) simply consists of a programmable output enable, a feedback path, and flip-flop (except ispMACH 4A devices with 1:1 macrocell-I/O cell ratio). An individual output enable product term is provided for each I/O cell. The feedback signal drives the input switch matrix.

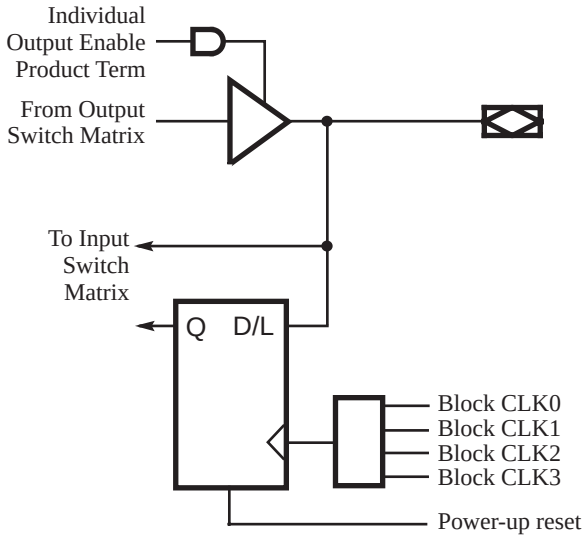


Figure 10. I/O Cell for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

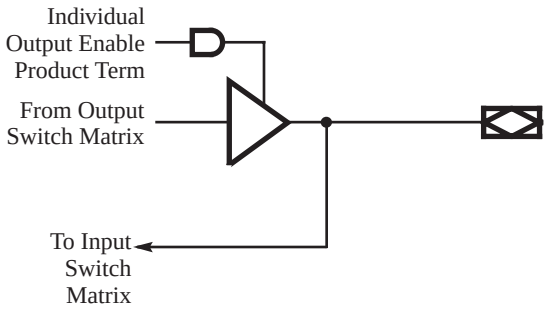


Figure 11. I/O Cell for ispMACH 4A Devices with 1:1 Macrocell-I/O Cell Ratio

The I/O cell (Figure 10) contains a flip-flop, which provides the capability for storing the input in a D-type register or latch. The clock can be any of the PAL block clocks. Both the direct and registered versions of the input are sent to the input switch matrix. This allows for such functions as "time-domain-multiplexed" data comparison, where the first data value is stored, and then the second data value is put on the I/O pin and compared with the previous stored value.

Note that the flip-flop used in the ispMACH 4A I/O cell is independent of the flip-flops in the macrocells. It powers up to a logic low.

Zero-Hold-Time Input Register

The ispMACH 4A devices have a zero-hold-time (ZHT) fuse which controls the time delay associated with loading data into all I/O cell registers and latches. When programmed, the ZHT fuse increases the data path setup delays to input storage elements, matching equivalent delays in the clock path. When the fuse is erased, the setup time to the input storage element is minimized. This feature facilitates doing worst-case designs for which data is loaded from sources which have low (or zero) minimum output propagation delays from clock edges.

Input Switch Matrix

The input switch matrix (Figures 12 and 13) optimizes routing of inputs to the central switch matrix. Without the input switch matrix, each input and feedback signal has only one way to enter the central switch matrix. The input switch matrix provides additional ways for these signals to enter the central switch matrix.

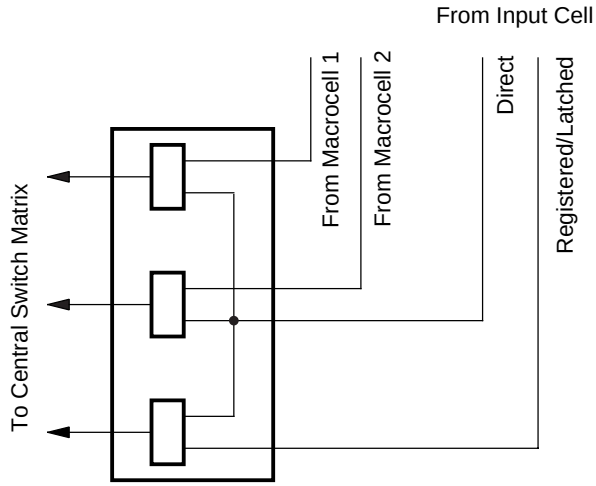


Figure 12. ispMACH 4A with 2:1 Macrocell-I/O Cell Ratio - Input Switch Matrix

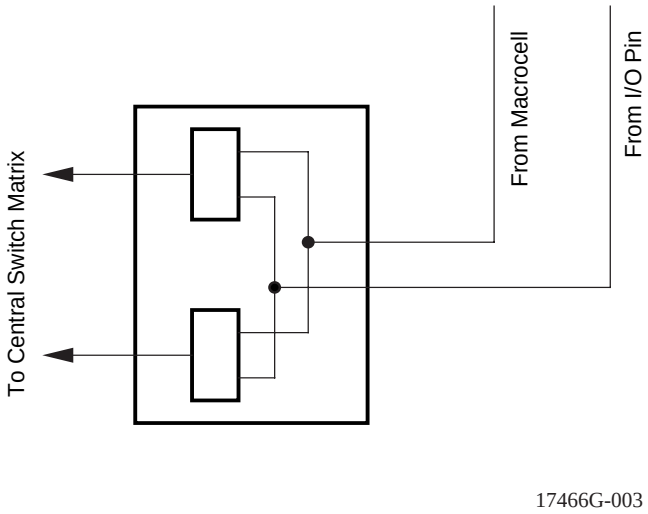
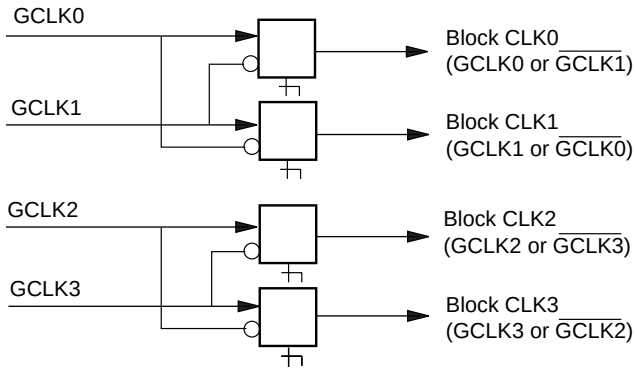


Figure 13. ispMACH 4A with 1:1 Macrocell-I/O Cell Ratio - Input Switch Matrix

PAL Block Clock Generation

Each ispMACH 4A device has four clock pins that can also be used as inputs. These pins drive a clock generator in each PAL block (Figure 14). The clock generator provides four clock signals that can be used anywhere in the PAL block. These four PAL block clock signals can consist of a large number of combinations of the true and complement edges of the global clock signals. Table 14 lists the possible combinations.



17466G-004

Figure 14. PAL Block Clock Generator [1]

1. M4A(3,5)-32/32 and M4A(3,5)-64/32 have only two clock pins, GCLK0 and GCLK1. GCLK2 is tied to GCLK0, and GCLK3 is tied to GCLK1.

Table 14. PAL Block Clock Combinations[1]

Block CLK0	Block CLK1	Block CLK2	Block CLK3
GCLK0	GCLK1	X	X
$\overline{\text{GCLK1}}$	GCLK1	X	X
GCLK0	$\overline{\text{GCLK0}}$	X	X
$\overline{\text{GCLK1}}$	$\overline{\text{GCLK0}}$	X	X
X	X	GCLK2 (GCLK0)	GCLK3 (GCLK1)
X	X	$\overline{\text{GCLK3}}$ ($\overline{\text{GCLK1}}$)	GCLK3 (GCLK1)
X	X	GCLK2 (GCLK0)	$\overline{\text{GCLK2}}$ ($\overline{\text{GCLK0}}$)
X	X	$\overline{\text{GCLK3}}$ ($\overline{\text{GCLK1}}$)	$\overline{\text{GCLK2}}$ ($\overline{\text{GCLK0}}$)

Note:

1. Values in parentheses are for the M4A(3,5)-32/32 and M4A(3,5)-64/32.

This feature provides high flexibility for partitioning state machines and dual-phase clocks. It also allows latches to be driven with either polarity of latch enable, and in a master-slave configuration.

weakly pulled up. For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

POWER MANAGEMENT

Each individual PAL block in ispMACH 4A devices features a programmable low-power mode, which results in power savings of up to 50%. The signal speed paths in the low-power PAL block will be slower than those in the non-low-power PAL block. This feature allows speed critical paths to run at maximum frequency while the rest of the signal paths operate in the low-power mode.

PROGRAMMABLE SLEW RATE

Each ispMACH 4A device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for the higher speed transition (3 V/ns) or for the lower noise transition (1 V/ns). For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise, and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed. The slew rate is adjusted independent of power.

POWER-UP RESET/SET

All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the control generator, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the control generator or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the V_{CC} rise must be monotonic, and the clock must be inactive until the reset delay time has elapsed.

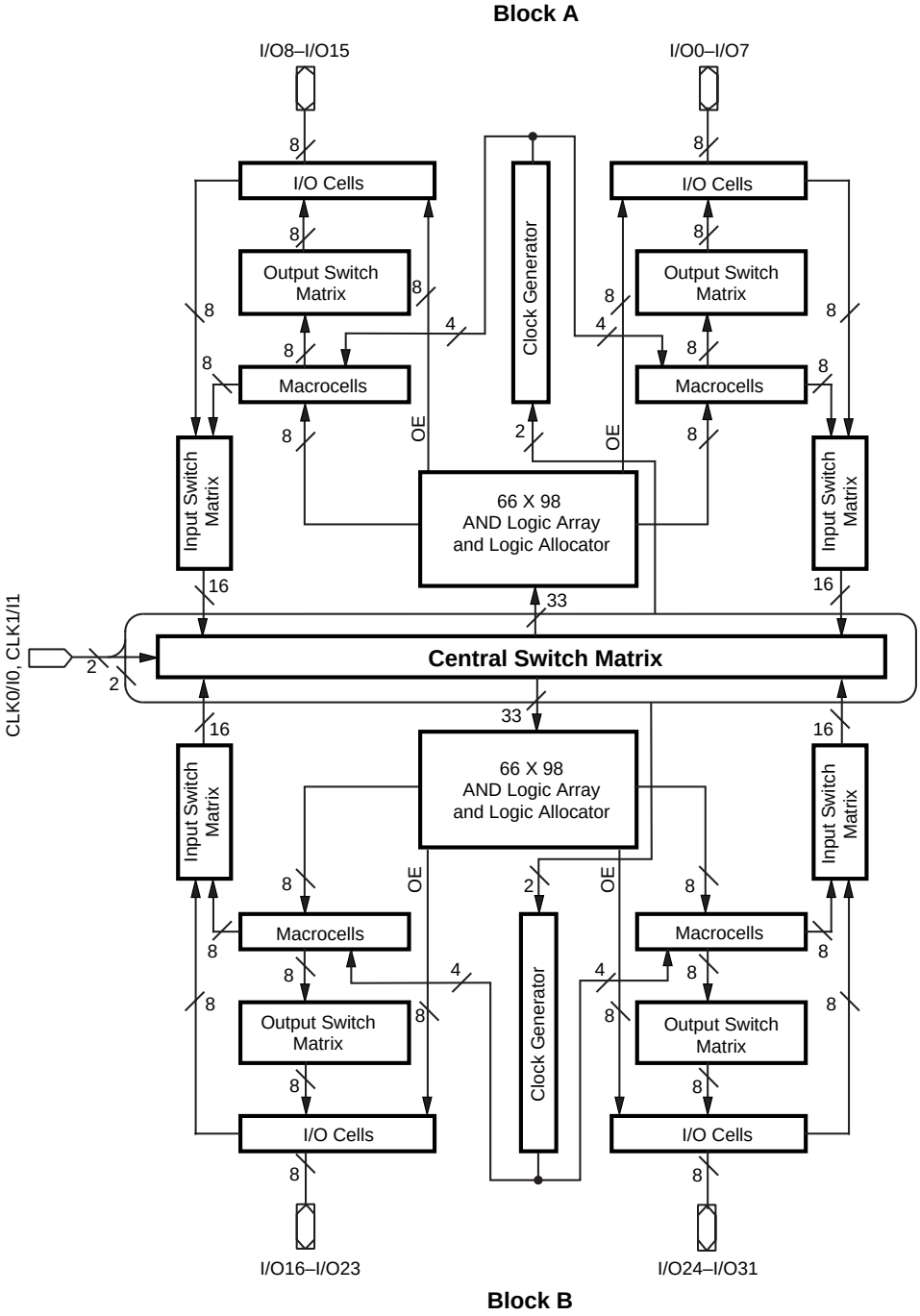
SECURITY BIT

A programmable security bit is provided on the ispMACH 4A devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

HOT SOCKETING

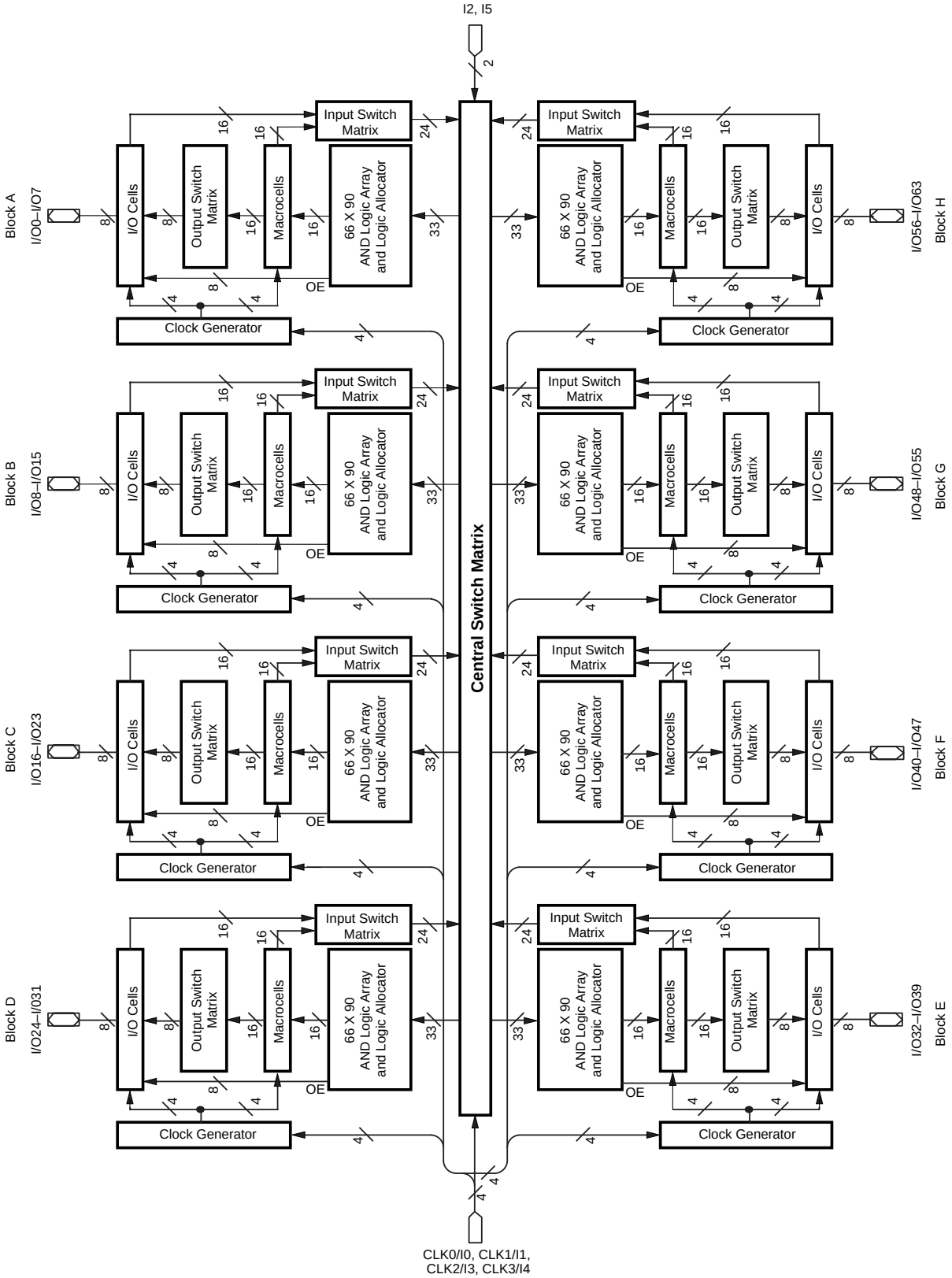
ispMACH 4A devices are well-suited for those applications that require hot socketing capability. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down MACH devices be minimal on active signals.

BLOCK DIAGRAM – M4A(3,5)-32/32



17466H-019

BLOCK DIAGRAM – M4A(3,5)-128/64



17466H-022

ABSOLUTE MAXIMUM RATINGS

M4A5

Storage Temperature . . . . . -65°C to +150°C

Ambient Temperature
with Power Applied. . . . . -55°C to +100°C

Device Junction Temperature. . . . . +130°C

Supply Voltage
with Respect to Ground . . . . . -0.5 V to +7.0 V

DC Input Voltage . . . . . -0.5 V to V_{CC} + 0.5 V

Static Discharge Voltage . . . . . 2000 V

Latchup Current (T_A = -40°C to +85°C) . . . . . 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . . . 0°C to +70°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +4.75 V to +5.25 V

Industrial (I) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . . . -40°C to +85°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +4.50 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

5-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	I_{OH} = –3.2 mA, V_{CC} = Min, V_{IN} = V_{IH} or V_{IL}	2.4			V
		I_{OH} = -100 µA, V_{CC} = Max, V_{IN} = V_{IH} or V_{IL}		3.3	3.6	V
V_{OL}	Output LOW Voltage	I_{OL} = 24 mA, V_{CC} = Min, V_{IN} = V_{IH} or V_{IL} (Note 1)			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 2)	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 2)			0.8	V
I_{IH}	Input HIGH Leakage Current	V_{IN} = 5.25 V, V_{CC} = Max (Note 3)			10	µA
I_{IL}	Input LOW Leakage Current	V_{IN} = 0 V, V_{CC} = Max (Note 3)			–10	µA
I_{OZH}	Off-State Output Leakage Current HIGH	V_{OUT} = 5.25 V, V_{CC} = Max, V_{IN} = V_{IH} or V_{IL} (Note 3)			10	µA
I_{OZL}	Off-State Output Leakage Current LOW	V_{OUT} = 0 V, V_{CC} = Max , V_{IN} = V_{IH} or V_{IL} (Note 3)			–10	µA
I_{SC}	Output Short-Circuit Current	V_{OUT} = 0.5 V, V_{CC} = Max (Note 4)	–30		–160	mA

Notes:

1. *Total I_{OL} for one PAL block should not exceed 64 mA.*
2. *These are absolute values with respect to device ground, and all overshoots due to system or tester noise are included.*
3. *I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).*
4. *Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. V_{OUT} = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.*

ABSOLUTE MAXIMUM RATINGS

M4A3

Storage Temperature . . . . . -65°C to +150°C

Ambient Temperature
with Power Applied. . . . . -55°C to +100°C

Device Junction Temperature. . . . . +130°C

Supply Voltage
with Respect to Ground . . . . . -0.5 V to +4.5 V

DC Input Voltage . . . . . -0.5 V to 6.0 V

Static Discharge Voltage . . . . . 2000 V

Latchup Current (T_A = -40°C to +85°C) . . . . . 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . . . 0°C to +70°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . . . -40°C to +85°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +3.0 V to +3.6 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions		Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	V_{CC} = Min, V_{IN} = V_{IH} or V_{IL}	I_{OH} = –100 µA	V_{CC} – 0.2			V
			I_{OH} = –3.2 mA	2.4			V
V_{OL}	Output LOW Voltage	V_{CC} = Min, V_{IN} = V_{IH} or V_{IL} (Note 1)	I_{OL} = 100 µA			0.2	V
			I_{OL} = 24 mA			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs		2.0		5.5	V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs		–0.3		0.8	V
I_{IH}	Input HIGH Leakage Current	V_{IN} = 3.6 V, V_{CC} = Max (Note 2)				5	µA
I_{IL}	Input LOW Leakage Current	V_{IN} = 0 V, V_{CC} = Max (Note 2)				–5	µA
I_{OZH}	Off-State Output Leakage Current HIGH	V_{OUT} = 3.6 V, V_{CC} = Max, V_{IN} = V_{IH} or V_{IL} (Note 2)				5	µA
I_{OZL}	Off-State Output Leakage Current LOW	V_{OUT} = 0 V, V_{CC} = Max, V_{IN} = V_{IH} or V_{IL} (Note 2)				–5	µA
I_{SC}	Output Short-Circuit Current	V_{OUT} = 0.5 V, V_{CC} = Max (Note 3)		–15		–160	mA

Notes:

1. *Total I_{OL} for one PAL block should not exceed 64 mA.*
2. *I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).*
3. *Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.*

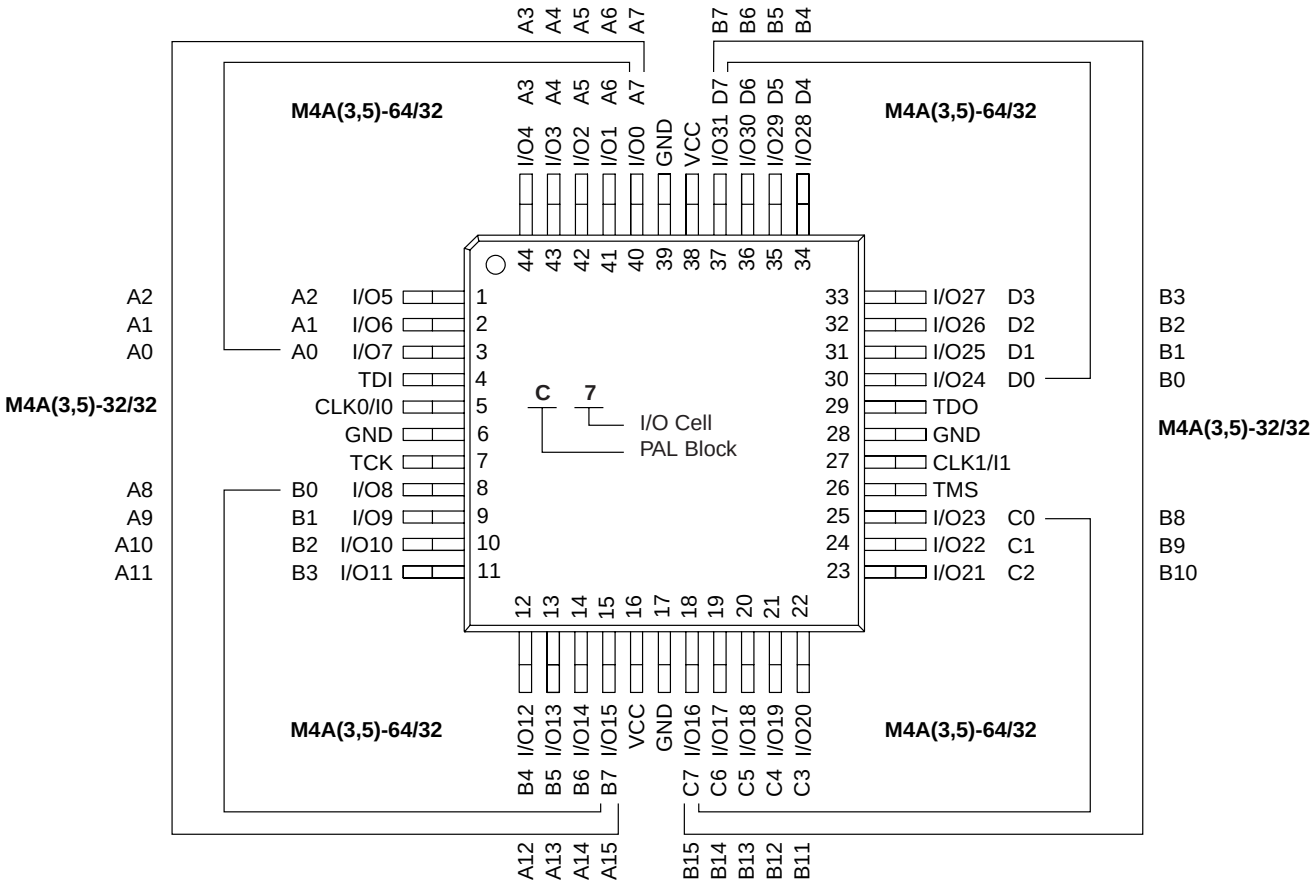
Notes:

1. *See "MACH Switching Test Circuit" document on the Literature Download page of the Lattice web site.*
2. *This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.*

44-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

44-Pin TQFP (1.0mm Thickness)



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

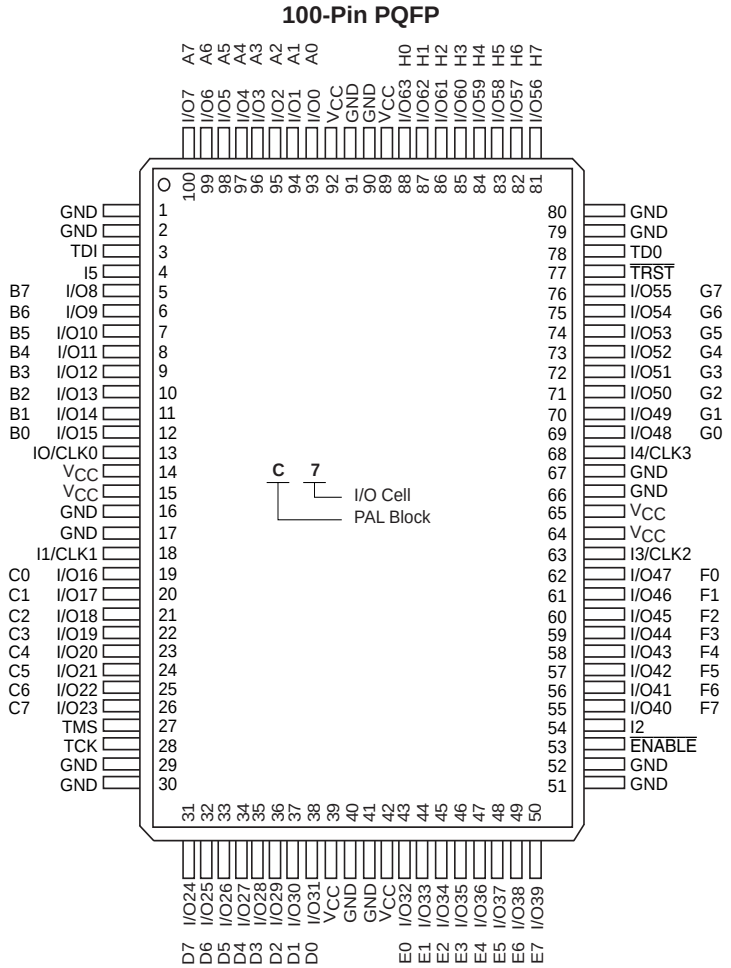
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN PQFP CONNECTION DIAGRAM (M4A(3,5)-128/64)

Top View



PIN DESIGNATIONS

I/CLK = Input or Clock

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

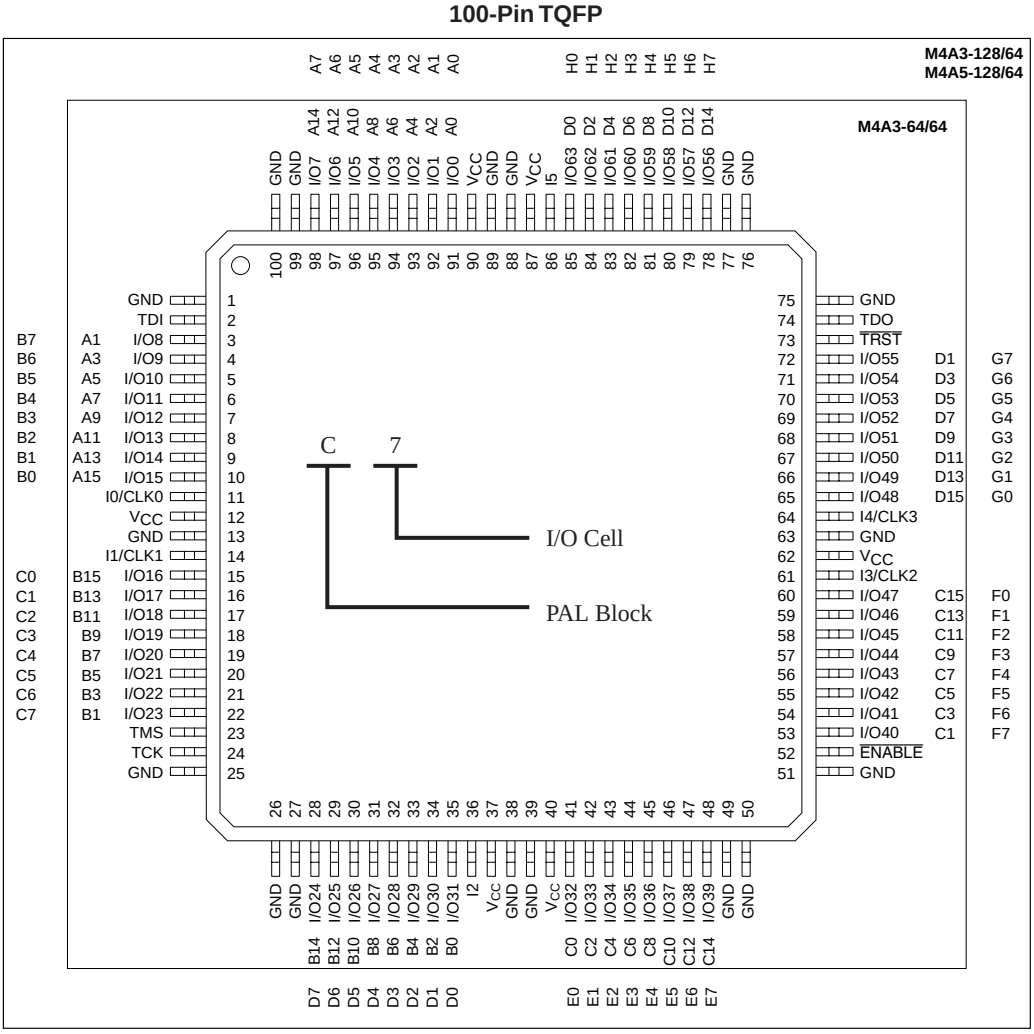
TDO = Test Data Out

$\overline{TRST}$ = Test Reset

$\overline{ENABLE}$ = Program

100-PIN TQFP CONNECTION DIAGRAM (M4A3-64/64 AND M4A(3,5)-128/64)

Top View



17466G-032a

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

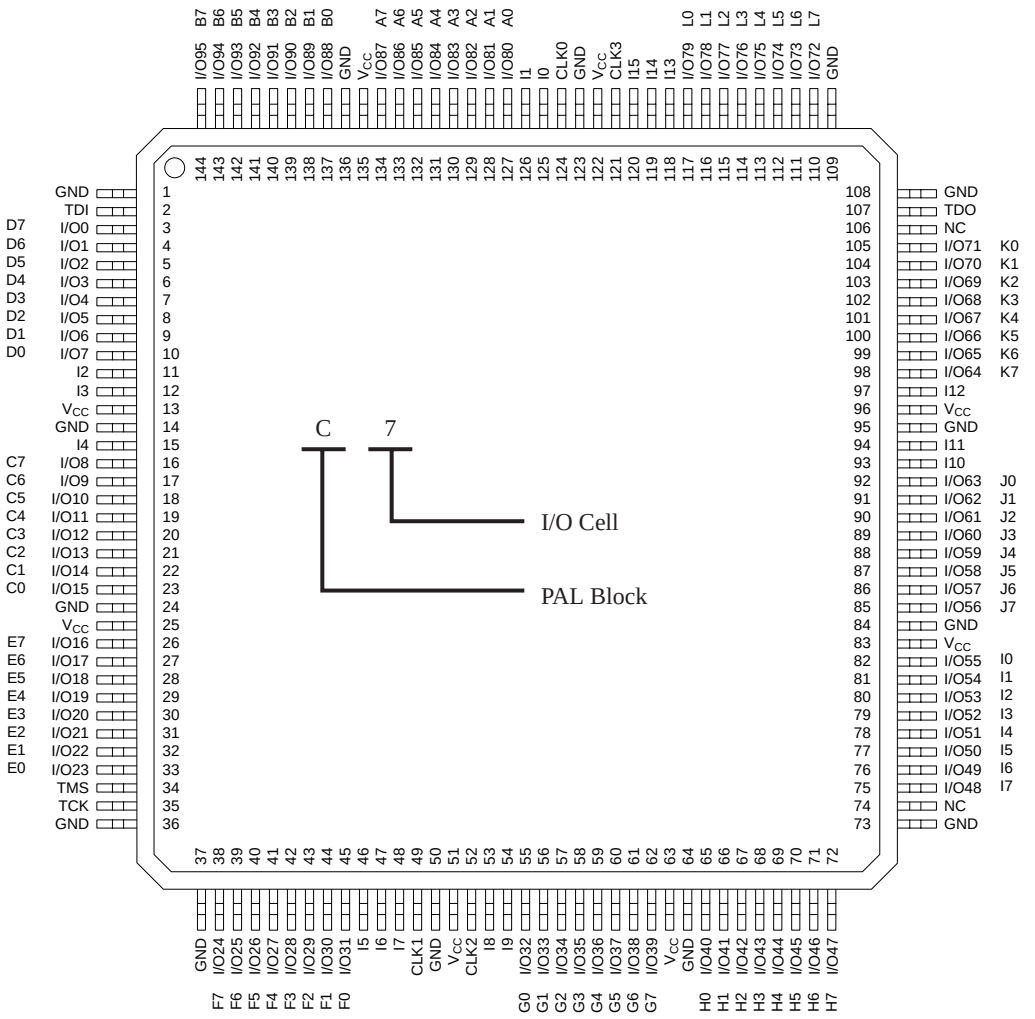
$\overline{TRST}$ = Test Reset

$\overline{ENABLE}$ = Program

144-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-192/96)

Top View

144-Pin TQFP



17466G-033

PIN DESIGNATIONS

CLK = Clock

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

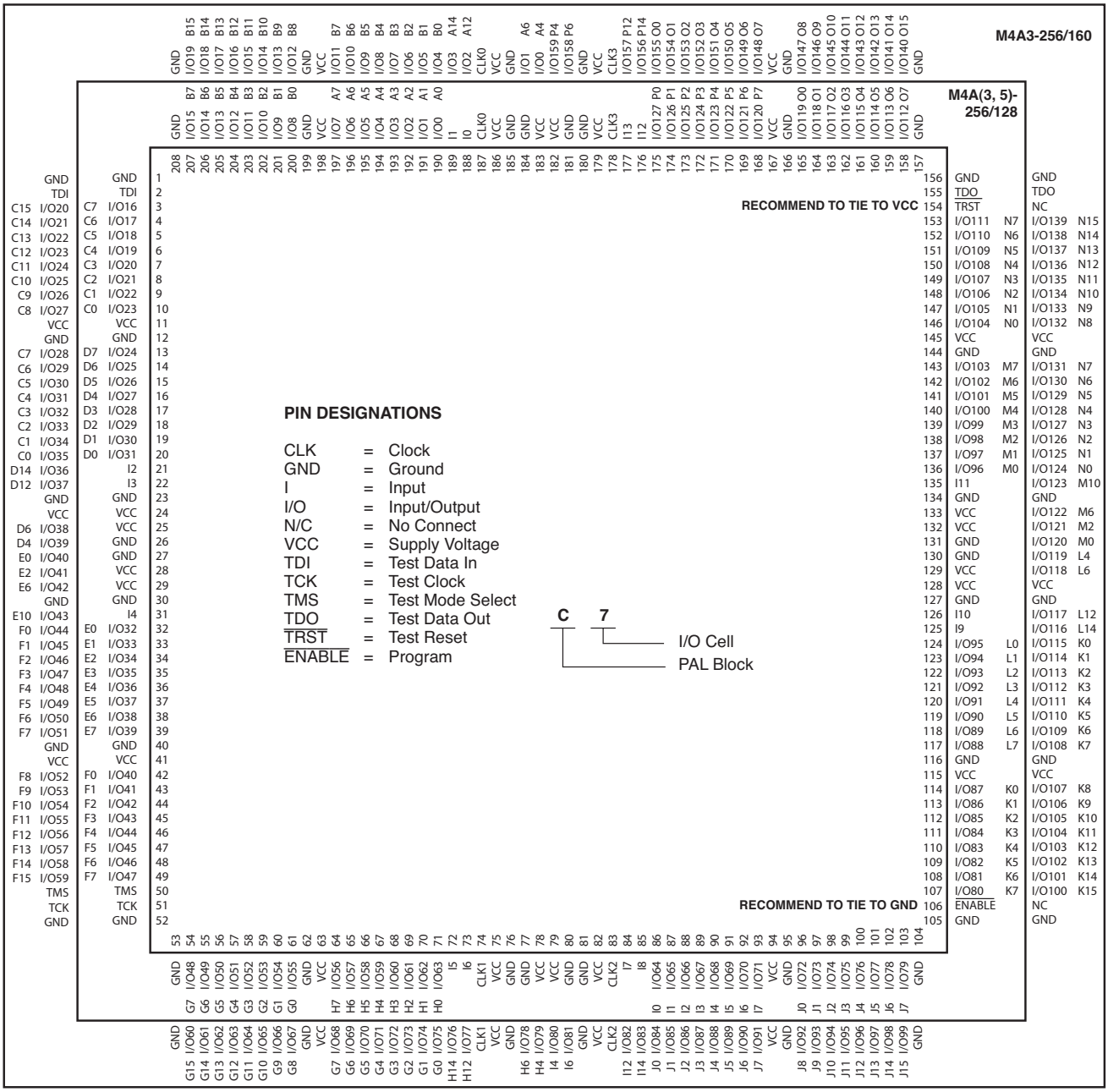
TMS = Test Mode Select

TDO = Test Data Out

208-PIN PQFP CONNECTION DIAGRAM (M4A(3,5)-256/128 AND M4A3-256/160)

Top View

208-Pin PQFP



17466G-044

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-512/192)

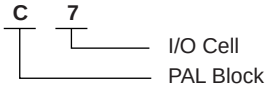
Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O159 KX7	I/O181 OX5	I/O180 OX4	I/O177 OX1	I/O174 NX6	I/O172 NX4	I/O191 PX7	I/O186 PX2	I/O1 A1	I/O3 A3	CLK0	I/O17 C1	I/O21 C5	I/O23 C7	I/O10 B2	I/O12 B4	**A**
B	I/O157 KX5	I/O158 KX6	I/O182 OX6	I/O179 OX3	I/O175 NX7	I/O173 NX5	I/O168 NX0	I/O187 PX3	I/O0 A0	I/O5 A5	I/O7 A7	I/O18 C2	I/O8 B0	I/O11 B3	I/O13 B5	N/C	**B**
C	I/O155 KX3	I/O156 KX4	N/C	I/O183 OX7	I/O178 OX2	I/O170 NX2	I/O171 NX3	I/O189 PX5	I/O184 PX0	I/O6 A6	I/O20 C4	I/O22 C6	I/O15 B7	I/O14 B6	TDI	I/O39 F7	**C**
D	I/O150 JX6	I/O151 JX7	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O38 F6	I/O37 F5	**D**
E	I/O148 JX4	N/C	I/O154 KX2	VCC	I/O152 KX0	I/O153 KX1	I/O190 PX6	CLK3	I/O188 PX4	I/O2 A2	I/O16 C0	N/C	GND	I/O36 F4	I/O35 F3	I/O47 G7	**E**
F	I/O144 JX0	I/O149 JX5	I/O147 JX3	GND	I/O146 JX2	I/O145 JX1	I/O176 OX0	I/O169 NX1	I/O185 PX1	I/O4 A4	I/O19 C3	I/O34 F2	VCC	I/O32 F0	I/O46 G6	I/O45 G5	**F**
G	I/O163 LX3	I/O166 LX6	I/O165 LX5	VCC	I/O164 LX4	I/O167 LX7	VCC	GND	GND	VCC	I/O33 F1	I/O44 G4	GND	I/O42 G2	I/O41 G1	I/O31 E7	**G**
H	I/O160 LX0	I/O162 LX2	I/O161 LX1	GND	I/O120 EX0	I/O121 EX1	GND	VCC	VCC	GND	I/O43 G3	I/O40 G0	VCC	I/O28 E4	I/O27 E3	I/O26 E2	**H**
J	I/O122 EX2	I/O123 EX3	I/O124 EX4	GND	I/O126 EX6	I/O125 EX5	GND	VCC	VCC	GND	I/O30 E6	I/O29 E5	GND	I/O65 L1	I/O64 L0	I/O66 L2	**J**
K	I/O127 EX7	I/O136 GX0	I/O137 GX1	VCC	I/O139 GX3	I/O138 GX2	VCC	GND	GND	VCC	I/O25 E1	I/O24 E0	VCC	I/O71 L7	I/O70 L6	I/O48 J0	**K**
L	I/O140 GX4	I/O141 GX5	I/O143 GX7	GND	I/O130 FX2	I/O142 GX6	I/O98 AX2	I/O91 P3	I/O75 N3	I/O77 N5	I/O68 L4	I/O67 L3	GND	I/O51 J3	I/O52 J4	I/O49 J1	**L**
M	I/O128 FX0	I/O129 FX1	I/O131 FX3	GND	I/O115 CX3	I/O113 CX1	I/O100 AX4	I/O90 P2	I/O74 N2	I/O80 O0	I/O83 O3	I/O69 L5	VCC	I/O60 K4	I/O55 J7	I/O50 J2	**M**
N	I/O132 FX4	I/O133 FX5	I/O135 FX7	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O56 K0	I/O53 J5	**N**
P	I/O134 FX6	I/O109 BX5	I/O110 BX6	I/O111 BX7	I/O116 CX4	I/O114 CX2	I/O101 AX5	I/O89 P1	I/O93 P5	I/O94 P6	I/O79 N7	I/O84 O4	I/O87 O7	TMS	I/O57 K1	I/O54 J6	**P**
R	I/O108 BX4	I/O107 BX3	I/O104 BX0	I/O119 CX7	I/O112 CX0	I/O102 AX6	I/O99 AX3	I/O96 AX0	I/O92 P4	I/O72 N0	I/O76 N4	I/O81 O1	I/O85 O5	I/O63 K7	I/O59 K3	I/O58 K2	**R**
T	I/O106 BX2	I/O105 BX1	I/O118 CX6	I/O117 CX5	I/O103 AX7	CLK2	I/O97 AX1	I/O88 P0	CLK1	I/O95 P7	I/O73 N1	I/O78 N6	I/O82 O2	I/O86 O6	I/O62 K6	I/O61 K5	**T**
	16	**15**	**14**	**13**	**12**	**11**	**10**	**9**	**8**	**7**	**6**	**5**	**4**	**3**	**2**	**1**	

PIN DESIGNATIONS

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
N/C = No Connect
VCC = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



m4a3.512.192_256bga

5V Commercial Combinations		
M4A5-32/32	-5, -7, -10,	JC, VC, VC48
M4A5-64/32	-55, -7, -10	JC, VC, VC48
M4A5-96/48		VC
M4A5-128/64		YC, VC
M4A5-192/96	-6, -7, -10	VC
M4A5-256/128	-65, -7, -10	YC

5V Industrial Combinations		
M4A5-32/32	-7, -10, -12	JI, VI, VI48
M4A5-64/32	-7, -10, -12	JI, VI, VI48
M4A5-96/48		VI
M4A5-128/64		YI, VI
M4A5-192/96	-7, -10, -12	VI
M4A5-256/128	-10, -12	YI

Lead-free Packaging

3.3V Commercial Combinations		
M4A3-32/32	-5, -7, -10	VNC, VNC48, JNC
M4A3-64/32	-55, -7, -10	VNC, VNC48, JNC
M4A3-64/64		VNC
M4A3-128/64		VNC
M4A3-192/96	-6, -7, -10	VNC
M4A3-256/128	-55, -7, -10	FANC, YNC
M4A3-256/160	-7, -10	YNC
M4A3-256/192		FANC
M4A3-384/192	-65, -10, -12	FANC
M4A3-512/192	-7, -10, -12	FANC

3.3V Industrial Combinations		
M4A3-32/32	-7, -10, -12	VNI, VNI48, JNI
M4A3-64/32		VNI, VNI48, JNI
M4A3-64/64		VNI
M4A3-128/64		VNI
M4A3-192/96	-10, -12	VNI
M4A3-256/128		FANI, YNI
M4A3-256/160		YNI
M4A3-256/192	-10, -12, -14	FANI
M4A3-384/192		FANI
M4A3-512/192		FANI

5V Commercial Combinations		
M4A5-32/32	-5, -7, -10	VNC, VNC48, JNC
M4A5-64/32	-55, -7, -10	VNC, VNC48, JNC
M4A5-96/48		VNC
M4A5-128/64		VNC, YNC
M4A5-192/96	-6, -7, -10	VNC
M4A5-256/128	-65, -7, -10	YNC

5V Industrial Combinations		
M4A5-32/32	-7, -10, -12	VNI, VNI48, JNI
M4A5-64/32		VNI, VNI48, JNI
M4A5-96/48		VNI
M4A5-128/64		VNI, YNI
M4A5-192/96		VNI
M4A5-256/128		YNI

Most ispMACH devices are dual-marked with both Commercial and Industrial grades. The Industrial speed grade is slower, i.e., M4A3-256/128-7YC-10YI

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local Lattice sales office to confirm availability of specific valid combinations and to check on newly released combinations.